

Response Under 37 CFR 1.116  
Expedited Procedure  
Examining Group 1734  
Appl. No. 09/830,490  
Response dated December 23, 2003  
Reply to Office Action of September 24, 2003  
Attorney Docket No. 1217-010666

### AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings of claims in the application:

#### Listing of Claims

Claim 1 (Currently Amended): A process for producing IC cards, comprising the steps of: continuously feeding a mount substrate having unevenness of components on the surface thereof and simultaneously feeding a pair of sheet members on both surface sides of the mount substrate in such a manner that the mount substrate is interposed between the pair of sheet members; feeding an adhesive in fluid condition on the surface of the sheet members; and regulating a distance between the pair of sheet members into a constant spacing and hardening the adhesive by interposing the mount substrate between the surfaces of the sheet members on which the adhesive is fed, wherein the distance between the sheet members is narrowed gradually.

Claim 2 (Previously Presented): A process for producing IC cards, comprising the steps of: continuously feeding a mount substrate and simultaneously feeding a pair of sheet members on both surface sides of the mount substrate in such a manner that the mount substrate is interposed between the pair of sheet members; feeding an adhesive in fluid condition on the surface of the sheet members; and

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regulating a distance between the pair of sheet members into a constant spacing and hardening the adhesive by interposing the mount substrate between the surfaces of the sheet members on which the adhesive is fed, wherein one of the pair of sheet members consists of a release sheet.

**Claim 3 (Previously Presented):** A process for producing IC cards, comprising the steps of: continuously feeding a mount substrate and simultaneously feeding a pair of sheet members on both surface sides of the mount substrate in such a manner that the mount substrate is interposed between the pair of sheet members, wherein at least one of the pair of sheet members consists of a release sheet;

feeding an adhesive in fluid condition on the surface of the sheet members; regulating a distance between the pair of sheet members into a constant spacing and hardening the adhesive by interposing the mount substrate between the surfaces of the sheet members on which the adhesive is fed;

stripping the release sheet from the mount substrate after the hardening of the adhesive; and sticking a laminate sheet member onto adhesive layer surface exposed as a result of the stripping of the release sheet.

**Claim 4 (Cancelled)**